Very Low Forward Voltage Trench-based Schottky Rectifier

Exceptionally Low $V_F = 0.50$ V at $I_F = 5$ A

Features

- Fine Lithography Trench–based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- Low Thermal Resistance
- High Surge Capability
- Pb-Free and Halide-Free Packages are Available

Typical Applications

- Switching Power Supplies including Notebook / Netbook Adapters, ATX and Flat Panel Display
- High Frequency and DC–DC Converters
- Freewheeling and OR-ing diodes
- Reverse Battery Protection
- Instrumentation

Mechanical Characteristics

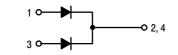
- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94-0 @ 0.125 in
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Maximum for 10 sec

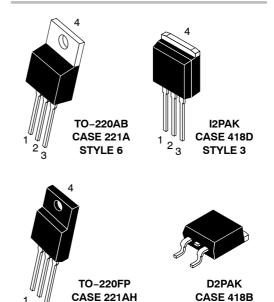


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PIN CONNECTIONS





ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

1

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	100	V
Average Rectified Forward Current (Rated V_R , T_C = 130°C)	Per device Per diode	I _{F(AV)}	20 10	A
Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz, T_C = 125°C)	Per device Per diode	I _{FRM}	40 20	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)		I _{FSM}	150	A
Operating Junction Temperature		TJ	-40 to +150	°C
Storage Temperature		T _{stg}	-40 to +150	°C
Voltage Rate of Change (Rated V _R)		dv/dt	10,000	V/μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

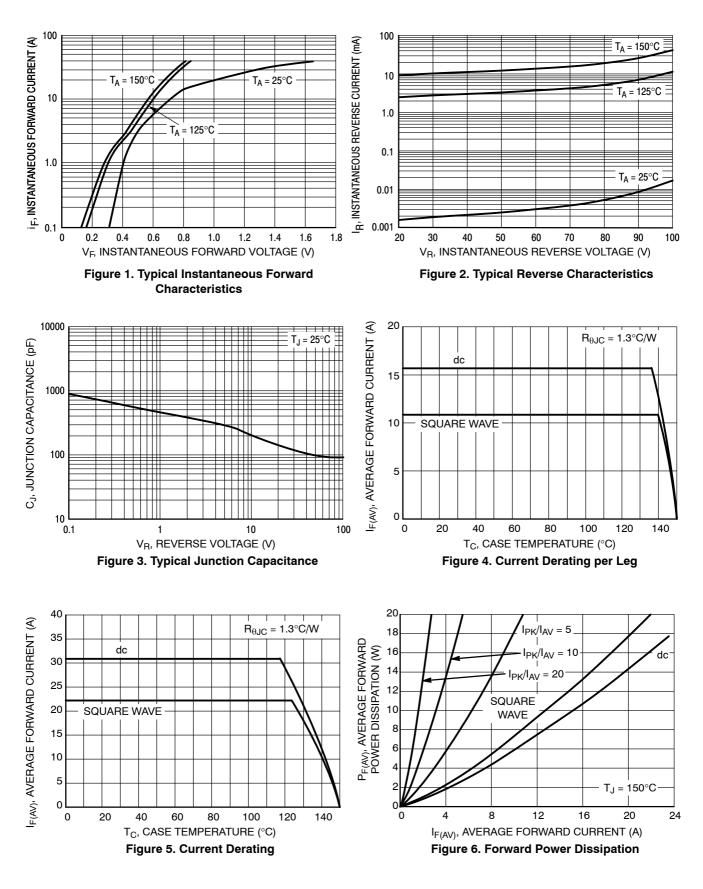
THERMAL CHARACTERISTICS

Rating	Symbol	NTST20U100CTG, NTSB20U100CT-1G	NTSB20U100CTG	NTSJ20U100CTG	Unit
Maximum Thermal Resistance per Diode Junction-to-Case Junction-to-Ambient	$R_{ heta JC} \\ R_{ heta JA}$	2.5 70	1.24 46.7	4.20 105	°C/W °C/W

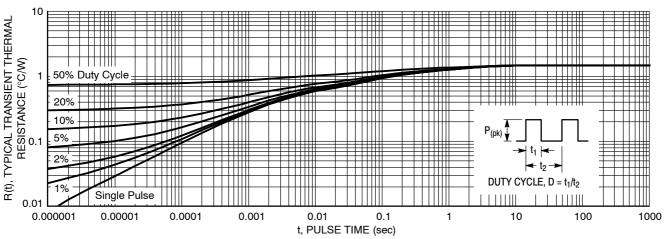
ELECTRICAL CHARACTERISTICS (Per Leg unless otherwise noted)

Rating	Symbol	Тур	Мах	Unit
Maximum Instantaneous Forward Voltage (Note 1)	٧ _F			V
$(I_F = 5 \text{ A}, T_J = 25^{\circ}\text{C})$ $(I_F = 10 \text{ A}, T_J = 25^{\circ}\text{C})$		0.55 0.65	0.79	
$(I_F = 5 \text{ A}, T_J = 125^{\circ}\text{C})$ $(I_F = 10 \text{ A}, T_J = 125^{\circ}\text{C})$		0.50 0.58	_ 0.68	
Maximum Instantaneous Reverse Current (Note 1) $(V_R = 70 \text{ V}, T_J = 25^{\circ}\text{C})$ $(V_R = 70 \text{ V}, T_J = 125^{\circ}\text{C})$	I _R	17 5.3		μA mA
(Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 125^{\circ}C$)		_ 12	800 25	μA mA

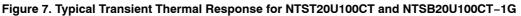
1. Pulse Test: Pulse Width = 300 $\mu s,$ Duty Cycle $\,\leq\,$ 2.0%

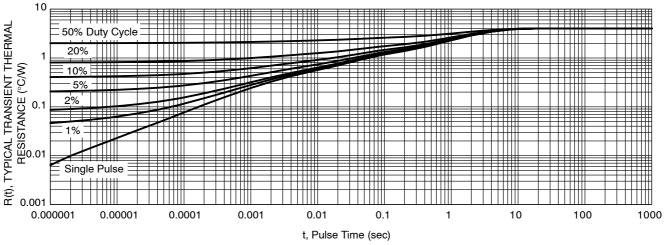


TYPICAL CHARACTERISITICS

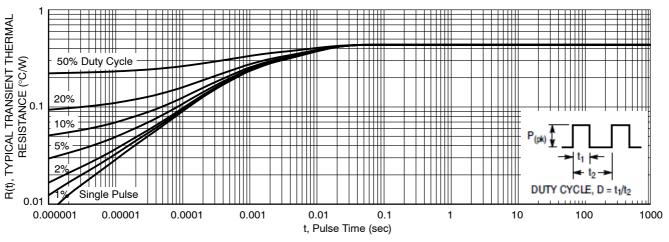


TYPICAL CHARACTERISITICS











ORDERING INFORMATION

Device	Package	Shipping	
NTST20U100CTG	TO-220AB (Pb-Free)	50 Units / Rail	
NTSB20U100CT-1G	l ² PAK (Pb–Free)	50 Units / Rail	
NTSJ20U100CTG	TO-220FP (Halide-Free)	50 Units / Rail	
NTSB20U100CTG	D ² PAK (Pb–Free)	50 Units / Rail	
NTSB20U100CTT4G	D ² PAK (Pb–Free)	800 / Tape & Reel	

AYWW AYWW TS20U10CG AYWW AYWW TS20U10CG TS20U10Cx TS20U10CG AKA AKA AKA AKA I²PAK TO-220FP D²PAK TO-220AB

Α	= Assembly Location

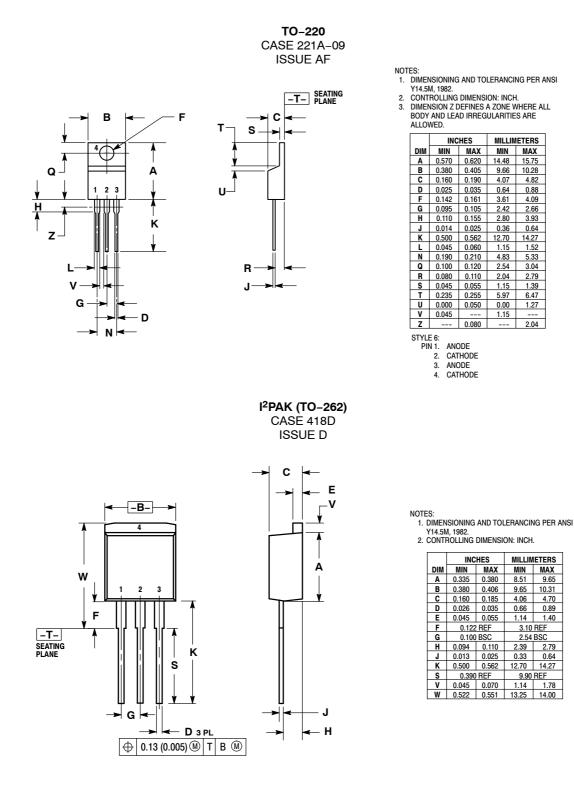
/ \	- / 000011
Y	= Year

ww = Work Week

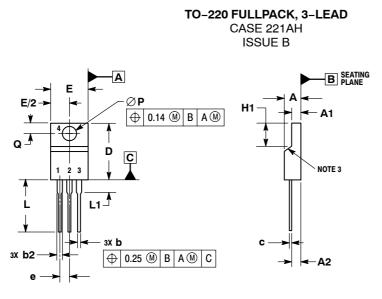
- AKA = Polarity Designator
- х = G or H
- G = Pb-Free Package
- н = Halide-Free Package

MARKING DIAGRAMS

PACKAGE DIMENSIONS



PACKAGE DIMENSIONS



NOTES:

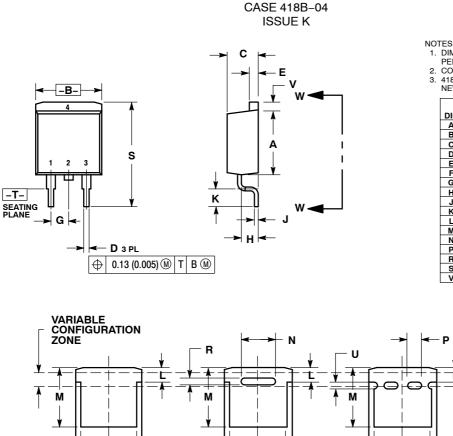
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. CONTOUL UNCONTROLLED IN THIS AREA. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE TO BE MEASURED AT OUTERMOST EXTREME OF THE PLASTIC BODY. 5. DIMENSION b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDEID AMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 2.00.

	MILLIMETERS			
DIM	MIN MAX			
Α	4.30	4.70		
A1	2.50	2.90		
A2	2.50	2.70		
b	0.54	0.84		
b2	1.10	1.40		
C	0.49	0.79		
D	14.70	15.30		
Е	9.70	10.30		
е	2.54	BSC		
H1	6.70	7.10		
L	12.70	14.73		
L1		2.80		
Ρ	3.00	3.40		
Q	2.80	3.20		

PACKAGE DIMENSIONS

D²PAK 3

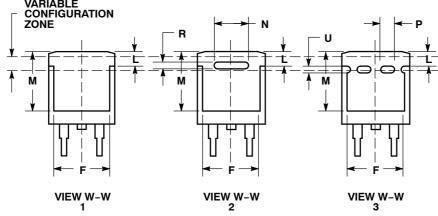


1. DIMENSIONING AND TOLERANCING

PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
в	0.380	0.405	9.65	10.29
С	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100	BSC	2.54 BSC	
н	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
κ	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
м	0.280	0.320	7.11	8.13
N	0.197	0.197 REF 5.0		REF
Р	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



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